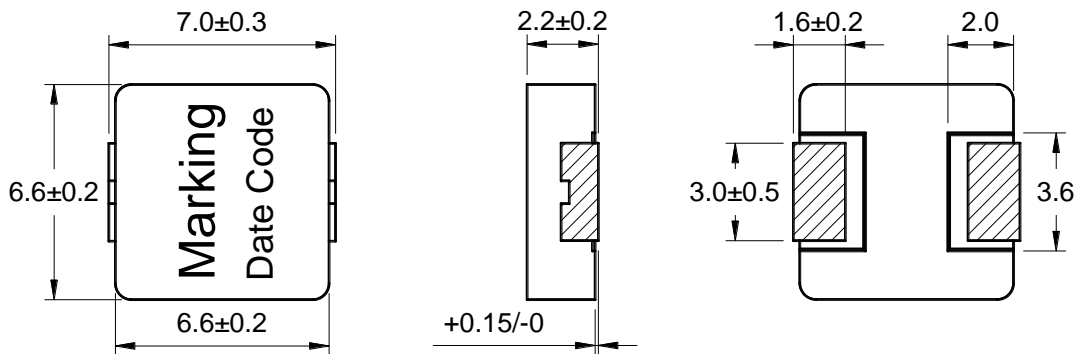


**Outline:  
产品概要**

- Magnetic shielded structure: excellent resistance to electro magnetic interference(EMI).  
磁屏蔽结构：抗电磁干扰(EMI)性能强。
- A composite structure, ultra low buzz noise.  
一体成型结构，超低蜂鸣噪音。
- Low loss, high efficiency, wide application frequency.  
低损耗，高效率，应用频率宽。
- Lightweight design, save space, suitable for high density SMT.  
轻薄型设计，节省空间，适合高密度贴装。
- Die-casting by low loss alloy powder: low impedance, small parasitic capacitance.  
低损耗合金粉末压铸：低阻抗，寄生电容小。
- Operating temperature : -40°C ~ +125°C (Including coil's temperature rise)  
工作温度：-40°C ~ +125°C (包含线圈发热)

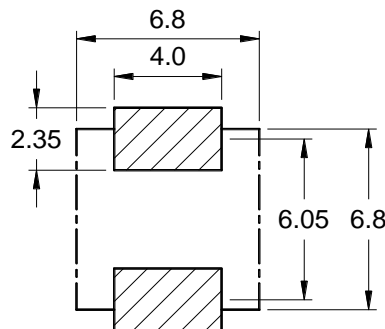
**1 Appearance and dimensions (mm)  
外形尺寸**



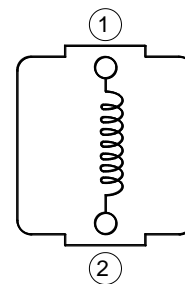
**2 Marking  
印字标识**



**3 Reference land pattern (mm)  
参考基板尺寸**



**4 Schematic  
原理图**



**5 Electrical characteristics**

**电气特性**

Part No. 型号	Inductance (μH) 电感值 ※1 ±20%	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2 Typical	Temperature rise current (A) 温升电流 ※3 Typical
		Typical	Max		
CSAB0724-2R2M	2.20	23.0	28.0	10.0	7.00
CSAB0724-3R3M	3.30	31.0	39.0	8.00	5.50
CSAB0724-4R7M	4.70	45.0	50.0	7.50	5.00
CSAB0724-100M	10.0	122	128	4.00	3.10

■ All data is tested based on 25°C ambient temperature.  
所有数据基于环境温度 25°C条件下测试。

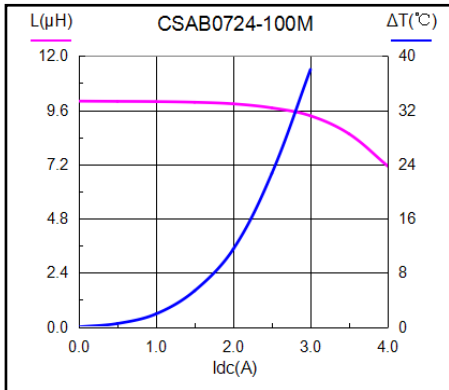
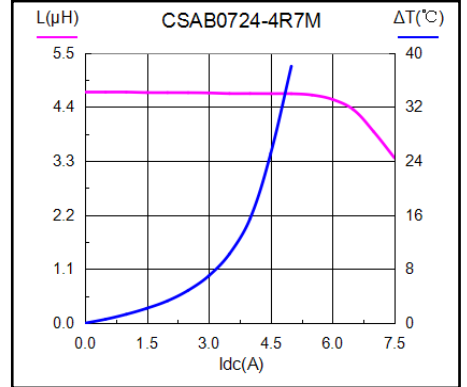
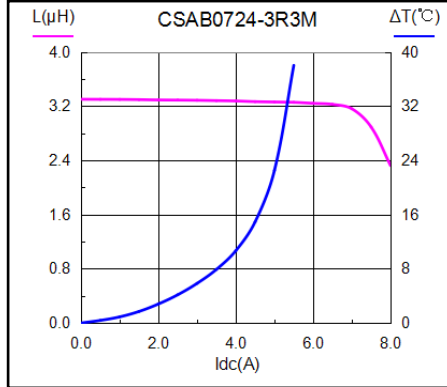
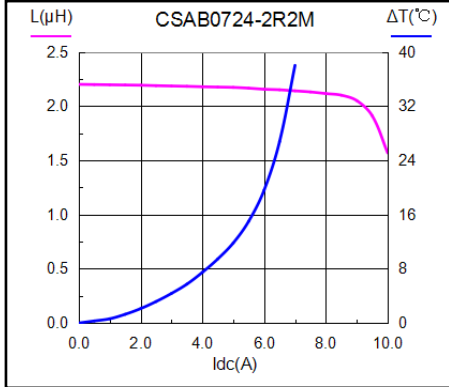
※1 Inductance measure condition at 100kHz, 1V.  
电感测试条件为 100kHz, 1V。

※2 Saturation current: the actual value of DC current when the inductance decrease 30% of its initial value.  
饱和电流: 电感值下降其初始值的 30%时所加载的实际直流电流值。

※3 Temperature rise current: the actual value of DC current when the temperature rise is ΔT40°C(Ta=25°C).  
温升电流: 使产品温度上升到 ΔT40°C时所加载的实际直流电流值(Ta=25°C)。

※ Special remind: Circuit design, component placement, PWB size and thickness, cooling system and etc. all will affect the product temperature. Please verify the product temperature in the final application.  
特别提醒: 线路设计, 组件布局, 印刷线路板(PWB)尺寸及厚度, 散热系统等均会影响产品温度。  
请务必在最终应用时, 验证产品发热状况。

**6 Saturation current VS temperature rise current curve  
饱和电流 VS 温升电流曲线**

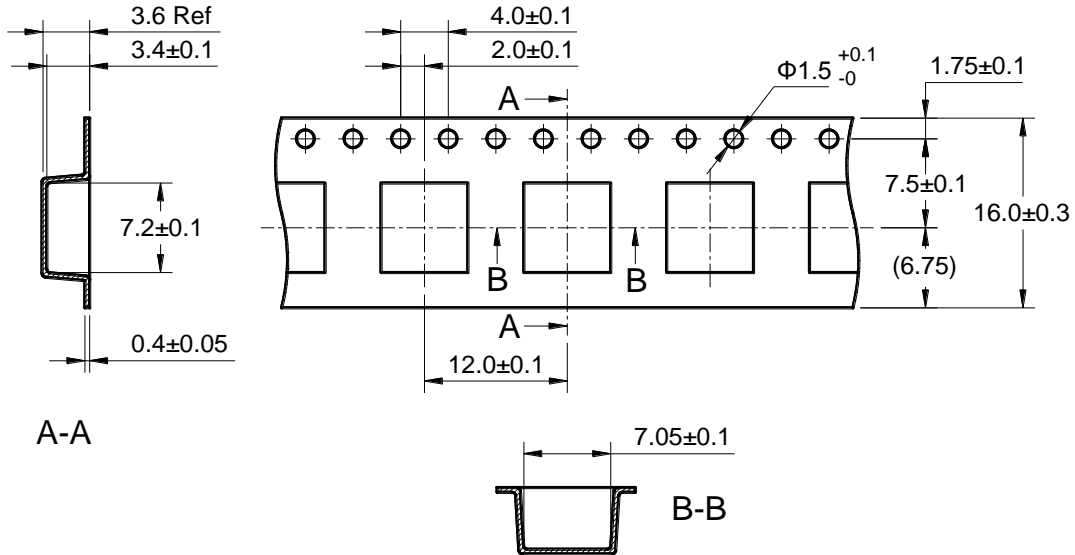


**7 Packing specification**

**包装规格**

**7.1 Carrier tape dimensions (mm)**

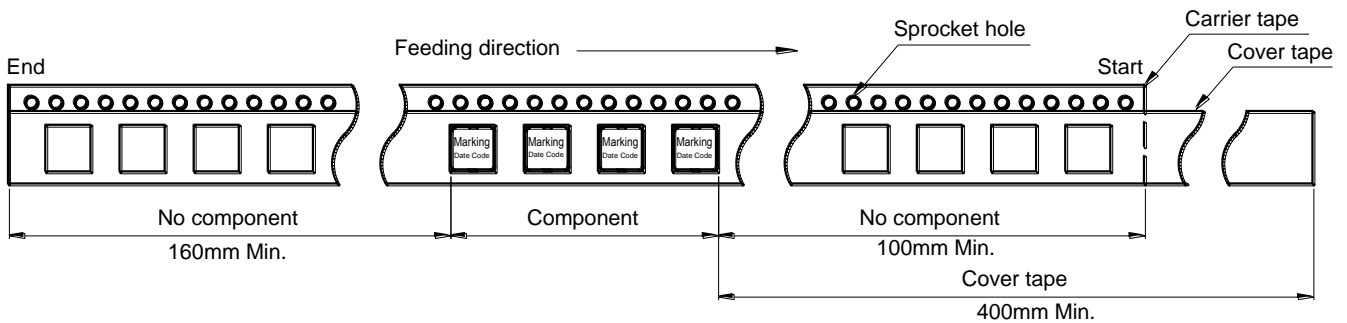
**载带尺寸**



※ Packing is referred to the international standard IEC 60286-3.  
包装参照国际标准 IEC 60286-3。

**7.2 Tape direction**

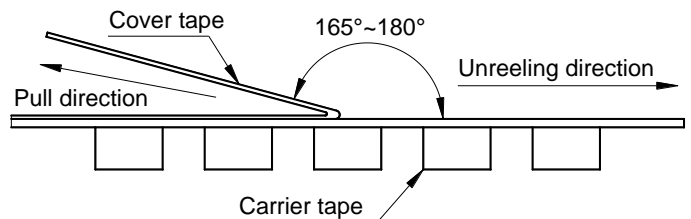
**捆包方向**



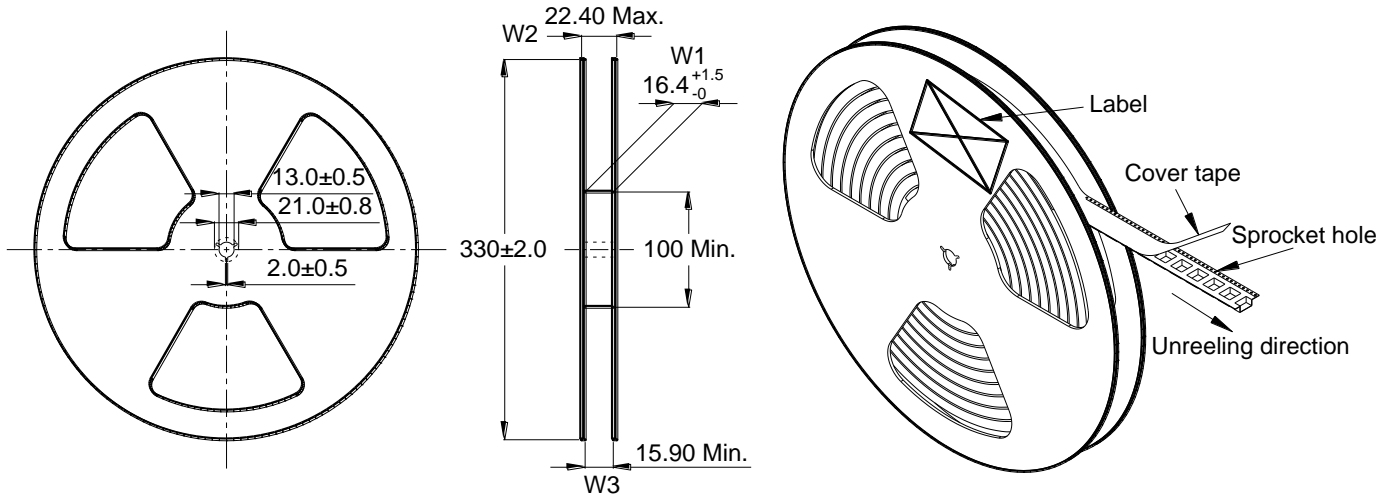
**7.3 Cover tape peel off condition**

**盖带剥离条件**

- Cover tape peel force shall be 0.1 to 1.3N.  
盖带剥离力度为 0.1~1.3N。
- Reference peel speed 300±10mm/min.  
参考剥离速度 300±10mm/分钟。



**7.4 Reel dimensions (mm)**  
卷盘尺寸



**7.5 Carton dimensions**  
包装箱尺寸

- Inner Carton: 340×340×95mm  
内包装盒
- Out Carton : 355×355×385mm  
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 总包装数量
CSAB0724	1000pcs	3000pcs = (3×1000)	9000pcs = (3×3000)

**7.6 Label making**  
标签标识

The following items will be marked on the reel of product label and shipping label.  
以下项目将明确标识于产品卷盘标签以及运输标签上。

**Production Label  
产品标签**

- Part No.  
产品型号
- Electrical Information  
产品电性信息
- Quantity  
数量
- Packing No.  
包装流水号

**Shipping Label  
运输标签**

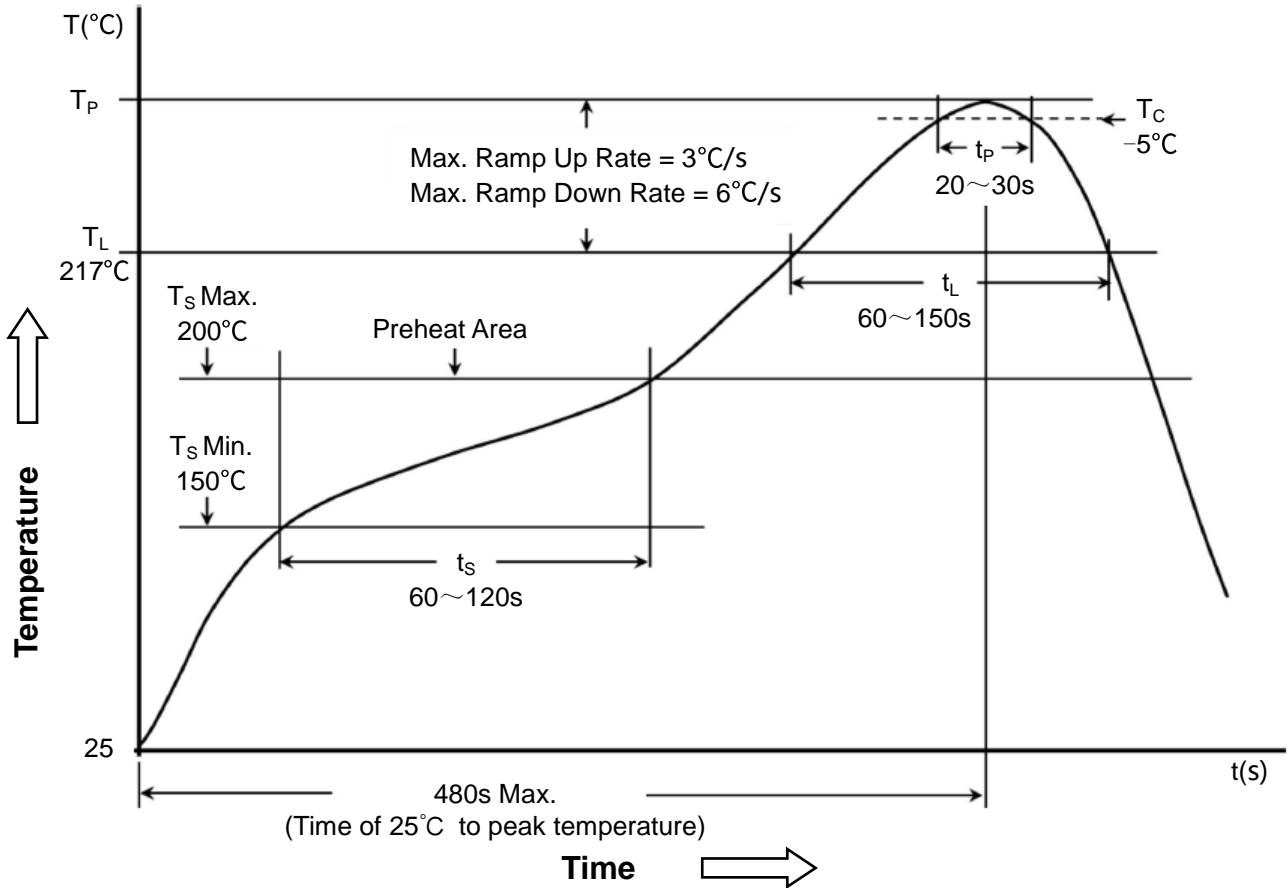
- Customer Name  
客户名称
- Customer Part No.  
客户型号
- Supplier Part No.  
供应商型号
- Supplier Name  
供应商名称
- Country of origin  
产品产地

**8 Soldering specification**

**焊接规格**

8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (Tp)

封装体峰值温度(Tp)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm <sup>3</sup>	350~2000 mm <sup>3</sup>	>2000 mm <sup>3</sup>
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.  
回流焊参照标准 IPC/JEDEC J-STD-020D。